



# Corporate Overview

March 5, 2026

# Forward-looking statements

Except for statements of historical fact, this presentation contains forward-looking statements (within the meaning of the federal securities laws) including statements related to future revenue, future earnings, and the success of our product releases, and the benefits and timing of the acquisition of Celestial AI that involve risks and uncertainties. Words such as “anticipates,” “expects,” “intends,” “plans,” “projects,” “believes,” “seeks,” “estimates,” “forecasts,” “targets,” “may,” “can,” “will,” “would” and similar expressions identify such forward-looking statements. These statements are not guarantees of results and should not be considered as an indication of future activity or future performance. Actual events or results may differ materially from those described in this presentation due to a number of risks and uncertainties.

Forward-looking statements are only predictions and are subject to risks, uncertainties and assumptions that are difficult to predict, including those described in the “Risk Factors” section of our Annual Reports on Form 10-K, Quarterly Reports on Form 10-Q and other documents filed by us from time to time with the SEC. Forward-looking statements speak only as of the date they are made. You are cautioned not to put undue reliance on forward-looking statements, and no person assumes any obligation to update or revise any such forward-looking statements, whether as a result of new information, future events or otherwise.

# Marvell closes previously announced acquisitions

**celestial AI™**

Pioneer of breakthrough  
**Photonic Fabric™**  
interconnect technology

**February 2, 2026**



Provider of **advanced**  
**PCIe and CXL**  
switching silicon

**February 10, 2026**

# Overview

Company founded

**1995**

FY26 revenue

**\$8.2B**

Employees

**7,700+**

Patents worldwide

**10,000+**

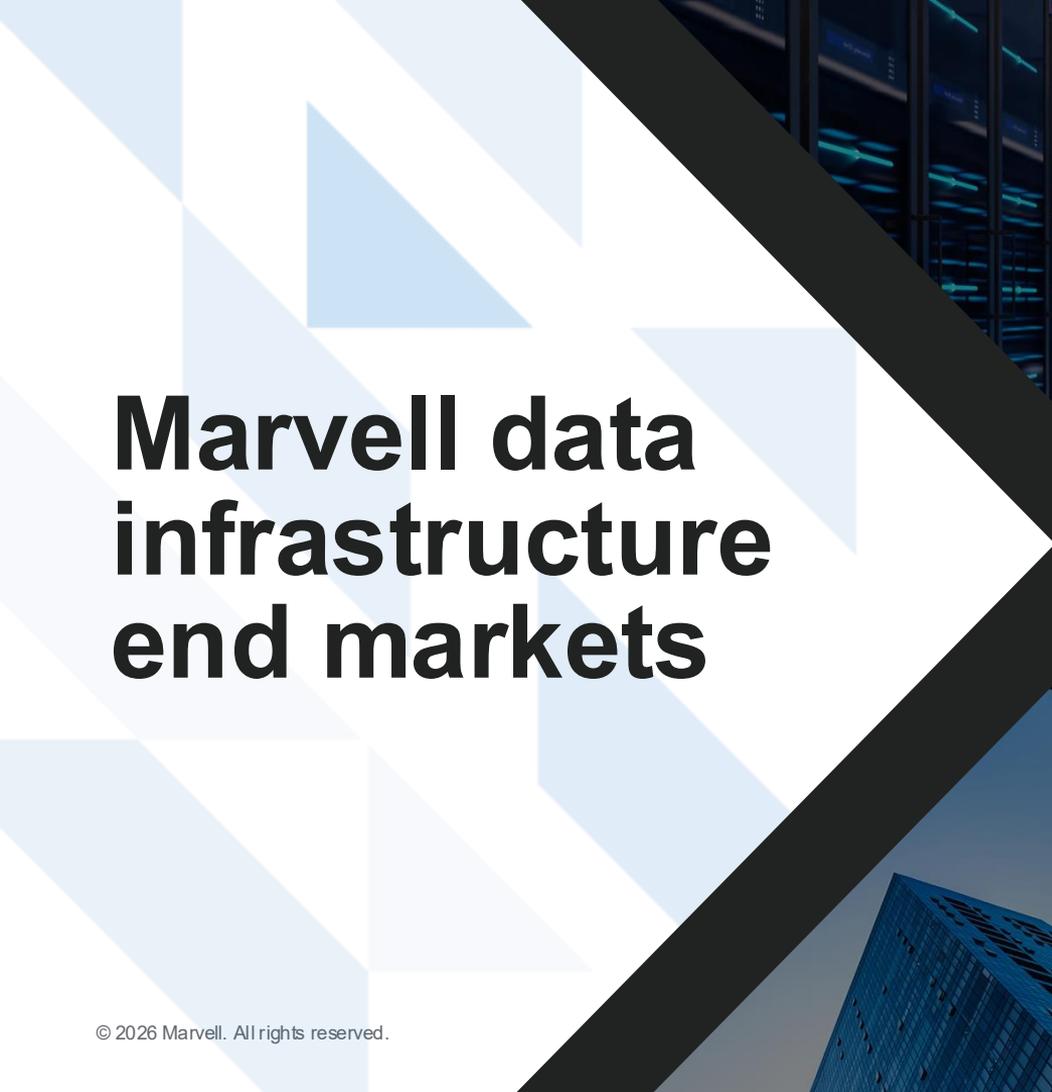
Global fabless semiconductor supplier



 Nasdaq -100

# Mission

We develop and deliver semiconductor solutions that **move, store, process and secure** the world's data faster and more reliably than anyone else.



# Marvell data infrastructure end markets

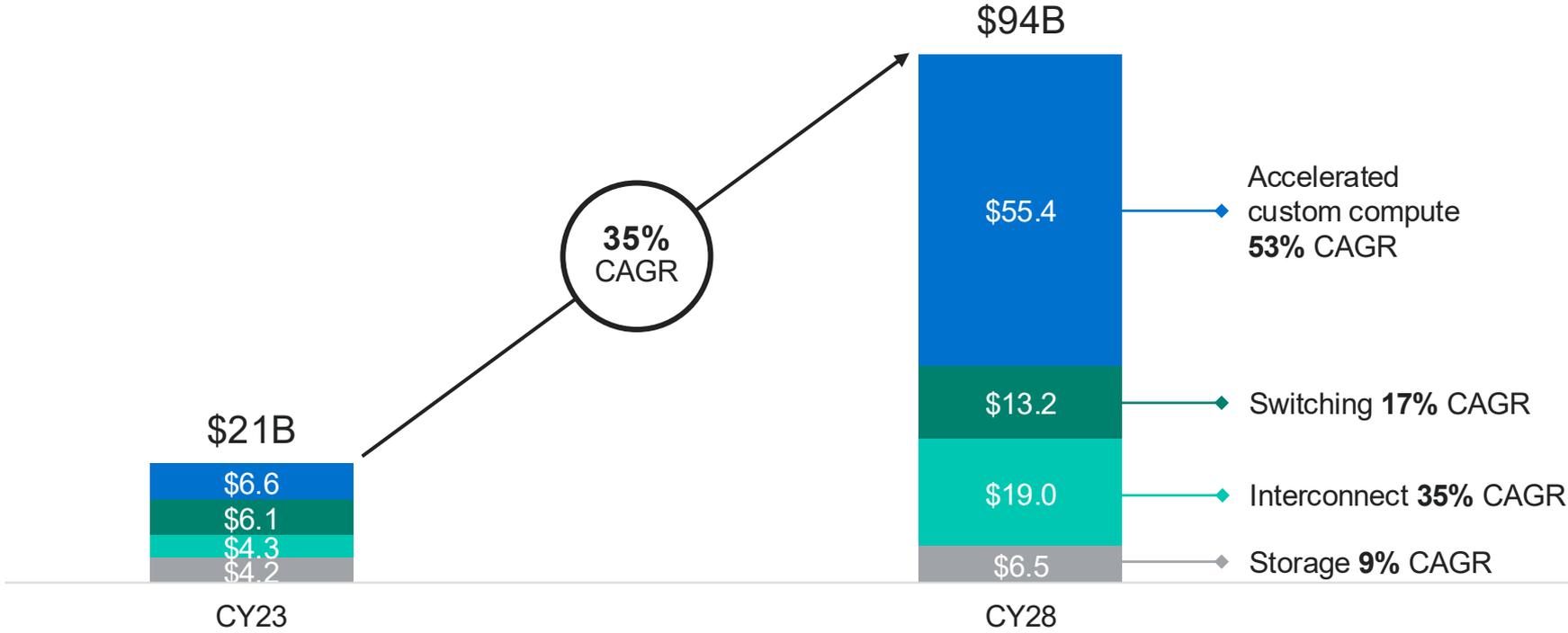


**Data center**



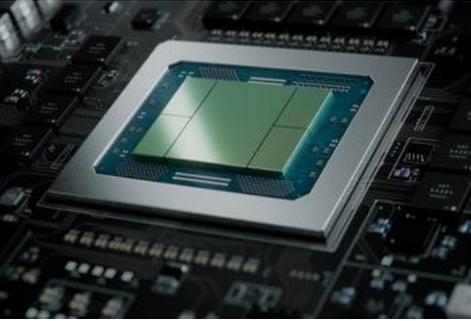
**Communications  
and other**

# Marvell data center market opportunity\*



\*As of Marvell Custom AI Investor Event, June 17, 2025  
 Source: 650 Group, CignalAI, Dell'Oro, LightCounting, and Marvell estimates

# Data center portfolio



## Custom

XPU |  
XPU attach (NIC, CXL,  
storage, security)



## Interconnect

PAM, coherent, coherent-lite and  
AEC DSPs | TIAs, drivers | DCI  
modules | PCIe and Ethernet  
retimers | Photonic Fabric™, CPO



## Switching

Ethernet, PCIe and CXL switches  
for scale-out, scale-up, and  
memory fabrics



## Storage

HDD and SSD controllers |  
Storage and memory  
accelerators

# Scale-up opportunity

Scale-up domain must move beyond the rack  
Copper hits reach, bandwidth limits  
Requires purpose-built switch and optical fabric

## Next-generation AI scale up



Multi-rack reach



Ultra-low latency



Very low power

## Switch

Orchestrates  
connectivity across  
scale-up domain

## Photonic Fabric™

Ultra high-bandwidth,  
low latency, low power  
multi-rack interconnect

# Marvell® Photonic Fabric™ technology platform

## Photonic Fabric™ scale-up network



- **30x** reach of passive copper
- **4x** bandwidth
- **4x** lower power
- **4x** lower latency
- **~1x** cost

**Platform for multi-rack AI scale up**

# Communications and other portfolio



## Compute

Wireless processors |  
Networking processors



## Interconnect

BASE-T PHYs |  
High-speed Ethernet PHYs



## Switching

Enterprise and industrial  
Ethernet switches

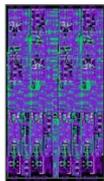


## Security

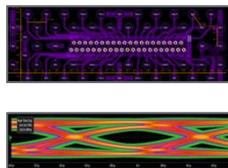
Hardware security modules |  
Security processors

# Essential silicon building blocks and IP

High-performance SerDes



Chip-to-chip (D2D) interconnect



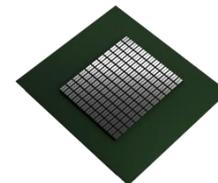
Ultra-high density and low-power SRAM



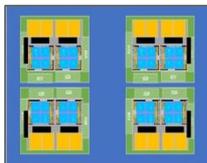
Custom HBM chiplet



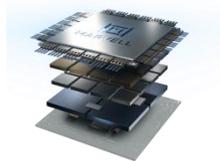
Package-integrated voltage regulation



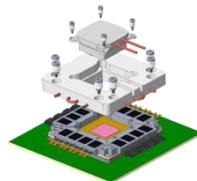
Advanced substrates



2.5D / 3D / 3.5D+ packaging



Advanced thermal solutions



3D SiPho integration

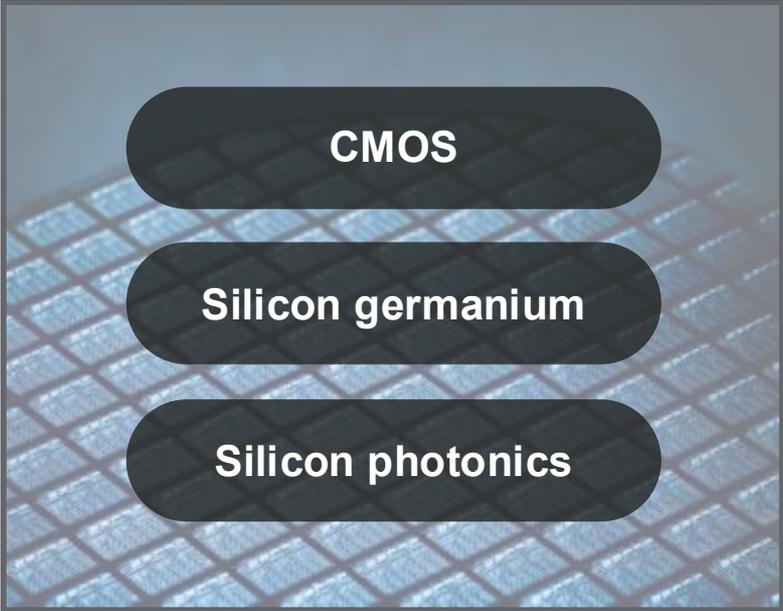


CPC/CPO



Pushing technology boundaries

# Marvell IP across process technologies



CMOS

Silicon germanium

Silicon photonics

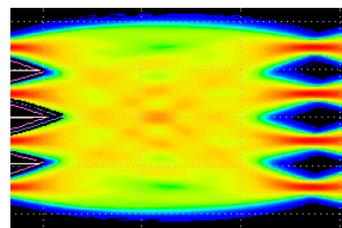
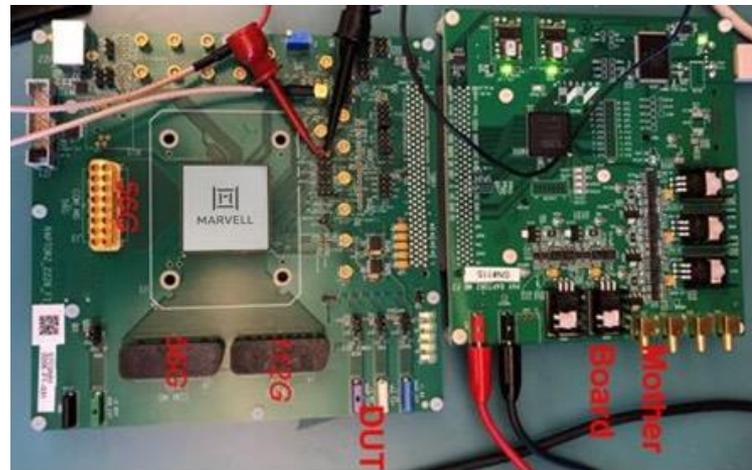


Foundries

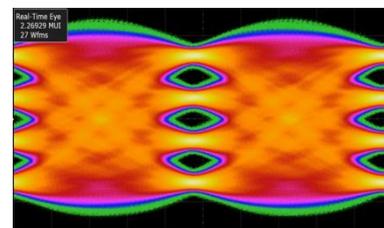
**Process-agnostic. Foundry-ready. Future-proof.**

# Delivering leading 5nm, 3nm and 2nm process platforms

- Optimized power-efficiency
- High-bandwidth performance
- Hyper-density
- Low latency



128G core capable of >40 dB



224G core capable of >40 dB

**Actively preparing for the Angstrom era**

# Flexible R&D models to satisfy customer needs

**\$ Buy**



**Standard**

**👤 Partner**



**Custom**  
(Marvell design)

Customer IP

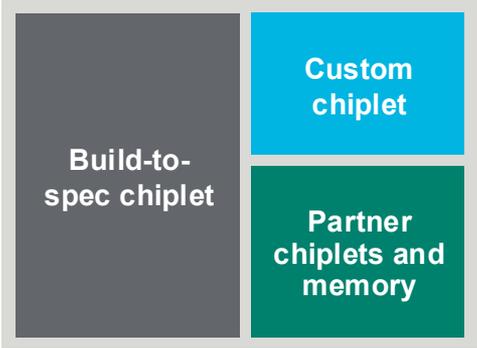
**🔧 Build**



**Custom**  
(Customer design)

Marvell IP

**🔄 Integrate**



Build-to-spec chiplet

Custom chiplet

Partner chiplets and memory

# Global presence



# Proven leadership team



**Matt Murphy**  
Chairman and  
Chief Executive Officer

Joined: July 2016



**Chris Koopmans**  
President and  
Chief Operating Officer

Joined: June 2016



**Sandeep Bharathi**  
President,  
Data Center Group

Joined: February 2019



**Mark Casper**  
Executive Vice President  
and Chief Legal Officer

Joined: October 2021



**Will Chu**  
Executive Vice President,  
Custom Cloud Solutions  
Business

Joined: August 2017



**Janice Hall**  
Executive Vice President  
and Chief Human  
Resources Officer

Joined: January 2017



**Gary Ignatin**  
Executive Vice President,  
Corporate Development

Joined: February 2017



**Dean Jarnac**  
Executive Vice President  
and Chief Sales Officer

Joined: April 2017



**David Lazovsky**  
Executive Vice President,  
Data Center Networking  
Business Group

Joined: February 2026



**Willem Meintjes**  
Chief Financial Officer

Joined: June 2016



**Noam Mizrahi**  
Executive Vice President  
and Corporate Chief  
Technology Officer

Joined: June 1998



**Achyut Shah**  
Senior Vice President,  
Multimarket Business Group

Joined: October 2020



**Xi Wang**  
Senior Vice President,  
Connectivity BU

Joined: April 2021



# Recent announcements

MARCH 5, 2026

**Marvell Extends ZR/ZR+ Leadership with Industry-first 1.6T ZR/ZR+ Pluggable and 2nm Coherent DSPs**

[NEWS LINK](#)

FEBRUARY 24, 2025

**Marvell to Showcase PCIe 8.0 SerDes Demonstration at DesignCon 2026**

[NEWS LINK](#)

DECEMBER 9, 2025

**Marvell Launches Strategic Initiative to Accelerate AEC Ecosystem and Hyperscaler Adoption**

[NEWS LINK](#)

DECEMBER 9, 2025

**Marvell Announces Adoption of Its PCIe Retimers by Leading AI and Data Center Infrastructure Providers**

[NEWS LINK](#)



Essential technology, done right™